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**METHOD FOR PROTECTING ELECTRONIC CIRCUIT COMPONENTS
AND ASSEMBLIES USING A METALLIZED FLEXIBLE ENCLOSURE**

ABSTRACT

An assembly for protecting the active electronic
5 components of an electronic product from the environment and
electromagnetic interference (EMI). A method is described
where the assembly is formed by providing a metallized
flexible enclosure around the electronic product, such as a
printed circuit board, and subsequently sealing the
10 metallized flexible enclosure, such that separable
connectors can be readily accessed without violating the
integrity of the seal. The metallized flexible enclosure
includes multiple layers of polymeric materials that provide
diffusion barrier properties and a metallic layer that
15 provides both diffusion barrier properties and EMI shielding
capabilities. The multiple layer sheet is patterned to
optimize the diffusion barrier properties and EMI shielding
capabilities. Further, the multiple layer sheet enables
efficient, high volume production. Thus, electronic
20 products can be provided with an assembly having an
environment protection capability and EMI shielding
capability amenable to reliable and cost effective high
volume production.

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